

# MULTILAYER CERAMIC CAPACITORS Capacitor Arrays Series (10V to 50V) 4 x 0402, 4 x 0603 Size NP0, X7R & Y5V Dielectrics RoHS Compliance

\*Contents in this sheet are subject to change without prior notice.

### **1. INTRODUCTION**

WTC middle and high voltage series MLCC is designed by a special internal electrode pattern, which can reduce voltage concentrations by distributing voltage gradients throughout the entire capacitor. This special design also affords increased capacitance values in a given case size and voltage rating.

WTC capacitor arrays are developed to offer designers the opportunity to lower placement costs increase assembly line output through lower component count per board.

## 2. FEATURES

- a. High density mounting due to mounting space saving.
- b. Mounting cost saving.
- c. Increased throughput.

## **3. APPLICATIONS**

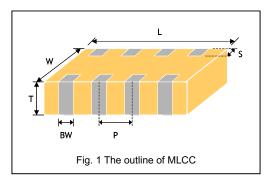
- a. For use as a bypass for digital and analog signal line noise
- b. Computer motherboards and peripherals.
- c. The other common electronic circuits.

# 4. HOW TO ORDER

Y	<u>4C</u>	<u>3</u>	<u>B</u>	<u>103</u>	<u>K</u>	<u>500</u>	<u>C</u>	Ī
Series	<u>Cap. Nr.</u>	Termination pitch	<b>Dielectric</b>	<u>Capacitance</u>	<u>Tolerance</u>	Rated voltage	Termination	Packaging
Y=Capacitor array		<b>3=</b> 0.03" pitch <b>2=</b> 0.02" pitch		Two significant digits followed by no. of zeros. And R is in place of decimal point.	J=±5% K=±10% M=±20% Z=-20/+80%	digits followed by no. of zeros.	<b>C</b> =Cu/Ni/Sn	T=7" reeled
				eg.: 103=10x10 <sup>3</sup> =10,000pF =10nF		eg.: 100=10 VDC 160=16 VDC 250=25 VDC 500=50 VDC		



## **5. EXTERNAL DIMENSIONS**



Size Inch (mm)	L (mm)	W (mm)	T (mm)/Sym	bol	S (mm)	BW (mm)	P (mm)
0508 (1220)	2.00±0.15	1.25±0.15	0.85±0.10	Т	0.20±0.10	0.25±0.10	0.50±0.10
0612 (1632)	3.20±0.15	1.60±0.15	0.80±0.10	В	0.30±0.20	0.40±0.15	0.80±0.15

Reflow soldering process only.

# **6. GENERAL ELECTRICAL DATA**

Dielectric	NP0		X7	Y5V	
Size	4x0402 4x0603		4x0402	4x0603	4x0603
Capacitance*	10pF to 270pF	10pF to 470pF	1000pF to 100nF	180pF to 100nF	10nF to 100nF
Capacitance tolerance**	rance** J (±5%), K (±10%)		K (±10%),	K (±10%), M (±20%)	
Rated voltage (WVDC)	50V 25, 50V 1		10V, 16V, 25V, 50V	16V, 25V, 50V	16V, 50V
Q/Tan δ*	Cap<30pF: Cap≥30pF		Ur=50V, ≤2.5% Ur=25V&16V, ≤3.5% Ur=10V, ≤5.0%		Ur=50V, ≤5% Ur=16V, ≤7%
Insulation resistance at Ur	≥10	GΩ	≥10GΩ (	chever is less	
Operating temperature		-55 to	) +125℃	-25 to +85℃	
Capacitance characteristic	±30ppm		±15%		+30/-80%
Termination			Ni/Sn (lead-free term	ination)	

\* Measured at 30~70% related humidity.

NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% at the conditions of 25°C ambient temperature.

X7R: Apply 1.0 $\pm$ 0.2Vrms, 1.0kHz $\pm$ 10%, at the conditions of 25°C ambient temperature.

Y5V: Apply 1.0±0.2Vrms, 1.0kHz±10%, at the conditions of 20℃ ambient temperature.

\*\* Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.



## 7. CAPACITANCE RANGE

	SIZE			4 x 0402						4 x 0603			
	DIELECTRIC		X7R		N	NP0 X7		X7R	R Y5V		5V		
R/	RATED VOLTAGE (VDC)		10	16	25	50	25	50	16	25	50	16	50
	10pF (100)	Т					В	В					
	15pF (150)	Т					В	В					
	22pF (220)	Т					В	В					
	33pF (330)	Т					В	В					
	47pF (470)	Т					В	В					
	68pF (680)	Т					В	В					
	100pF (101)	Т					В	В					
	150pF (151)	Т					В	В					
	180pF (181)	Т					В	В		В	В		
	220pF (221)	Т					В	В		В	В		
	270pF (271)	Т					В	В		В	В		
e	330pF (331)						В	В		В	В		
anc	470pF (471)						В	В		В	В		
acit	6,80pF (681)									В	В		
Capacitance	1,000pF (102)		Т	Т	Т	Т				В	В		
0	1,500pF (152)		Т	Т	Т	Т				В	В		
	2,200pF (222)		Т	Т	Т	Т				В	В		
	3,300pF (332)		Т	Т	Т	Т				В	В		
	4,700pF (472)		Т	Т	Т	Т				В	В		
	6,800pF (682)		Т	Т	Т	Т				В	В		
	0.010µF (103)		Т	Т	Т	Т				В	В		В
	0.015µF (153)		Т	Т	Т				В	В	В		В
	0.022µF (223)		Т	Т	Т				В	В	В		В
	0.033µF (333)		Т	Т	Т				В				В
	0.047µF (473)		Т	Т	Т				В				В
	0.068µF (683)		Т	Т	Т				В				В
	0.10µF (104)		Т	Т	Т				В			В	В

1. The letter in cell is expressed the symbol of product thickness.

# **8. PACKAGING DIMENSION AND QUANTITY**

Size	Thickness/Syn	nbol	Paper tape		
5120	(mm)		7" reel	13" reel	
4 x 0402	0.85±0.10	Т	4k	-	
4 x 0603	0.80±0.10	В	4k	-	

Unit: pieces



# 9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	ltem	Test Condition	Requirements			
1.	Visual and		* No remarkable defect.			
	Mechanical		* Dimensions to conform to individual specification sheet.			
2.	Capacitance	Class I: (NP0)	* Shall not exceed the limits given in the detailed spec.			
3.	Q/ D.F.	1.0±0.2Vrms, 1MHz±10%	NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C			
	(Dissipation	Class II: (X7R, Y5V)	X7R: Ur=50V, ≤2.5%; Ur=25V&16V, ≤3.5%; Ur=10V, ≤5.0%			
	Factor)	1.0±0.2Vrms, 1kHz±10%	Y5V: Ur=50V, ≤5%; Ur=16V, ≤7%			
4.	Dielectric	* To apply 250% rated voltage.	No evidence of damage or flash over during test.			
	Strength	* Duration: 1 to 5 sec.				
		* Charge and discharge current less than 50mA.				
5.	Insulation	To apply rated voltage for max. 120 sec.	≥10GΩ or RxC≥500Ω-F whichever is smaller.			
	Resistance					
6.	Temperature	With no electrical load.				
	Coefficient	T.C.         Operating Temp           NP0         -55~125 °C at 25 °C	T.C. Capacitance Change NP0 Within ±30ppm/℃			
		X7R -55~125°C at 25°C	X7R Within ±15%			
		Y5V -25~85℃ at 20℃	Y5V Within +30%/-80%			
7.	Adhesive	* Pressurizing force :	* No remarkable damage or removal of the terminations.			
1.	Strength of	5N (≤0603) and 10N (>0603)	no remarkable damage of removal of the terminations.			
	Termination	* Test time: 10±1 sec.				
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.			
0.	Resistance	* Total amplitude: 1.5mm	* Cap change and Q/D.F.: To meet initial spec.			
	Resistance	* Test time: 6 hrs. (Two hrs each in three mutually				
		perpendicular directions.)				
		* Measurement to be made after keeping at room temp. for				
		24±2 hrs.				
9.	Solderability	* Solder temperature: 235±5℃	95% min. coverage of all metalized area.			
	-	* Dipping time: 2±0.5 sec.				
10.	Bending Test	* The middle part of substrate shall be pressurized by means	* No remarkable damage.			
		of the pressurizing rod at a rate of about 1 mm per second until	* Cap change :			
		the deflection becomes 1 mm and then the pressure shall be	NP0: within $\pm 5.0\%$ or $\pm 0.5$ pF whichever is larger.			
		maintained for 5±1 sec.	X7R: within ±12.5%			
		* Measurement to be made after keeping at room temp. for	Y5V: within ±30%			
		24±2 hrs.	(This capacitance change means the change of capacitance under			
			specified flexure of substrate from the capacitance measured before			
			the test.)			
11.	Resistance to	* Solder temperature: 260±5℃	* No remarkable damage.			
	Soldering Heat	* Dipping time: 10±1 sec	* Cap change:			
		* Preheating: 120 to $150^{\circ}$ for 1 minute before imme rse the	NP0: within ±2.5% or ±0.25pF whichever is larger.			
		capacitor in a eutectic solder.	X7R: within ±7.5%			
		* Before initial measurement (Class II only): Perform	Y5V: within ±20%			
		150+0/-10℃ for 1 hr and then set for 24±2 hrs at r oom temp.	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.			
		* Measurement to be made after keeping at room temp. for	* 25% max. leaching on each edge.			
		24±2 hrs.				

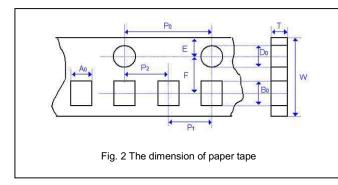


No.	ltem	Test Condition	Requirements		
12.	Temperature Cycle	* Conduct the five cycles according to the temperatures and time.            Step         Temp. (℃)         Time (min.)           1         Min. operating temp. +0/-3         30±3           2         Room temp.         2~3           3         Max. operating temp. +3/-0         30±3           4         Room temp.         2~3           *         Before initial measurement (Class II only): Perform           150+0/-10℃ for 1 hr and then set for 24±2 hrs at r oom temp.           *         Measurement to be made after keeping at room temp. for           24±2 hrs.	No remarkable damage. Cap change : NP0: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5% Y5V: within ±20% * Q/D.F., I.R. and dielectric strength: To meet initial requirements		
13.	Humidity (Damp Heat) Steady State	<ul> <li>* Test temp.: 40±2°C</li> <li>* Humidity: 90–95% RH</li> <li>* Test time: 500+24/-0hrs.</li> <li>*Before initial measurement (Class II only): Perform</li> <li>150+0/-10°C for 1 hr and then set for 24±2 hrs at r oom temp.</li> <li>* Measurement to be made after keeping at room temp. for</li> <li>24±2 hrs</li> </ul>	<ul> <li>* No remarkable damage.</li> <li>* Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5% Y5V: within ±30%</li> <li>* Q/D.F. value: NP0: Cap≥30pF, Q≥350; 10pF≤Cap&lt;30pF, Q≥275+2.5C Cap&lt;10pF; Q≥200+10C</li> <li>X7R: Ur=50V, ≤3%; Ur=25V&amp;16V, ≤5%; Ur=10V, ≤7.5% Y5V: Ur=50V, ≤7.5%; Ur=16V, ≤10%</li> <li>* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.</li> </ul>		
14.	Humidity (Damp Heat) Load	<ul> <li>* Test temp.: 40±2°C</li> <li>* Humidity: 90~95%RH</li> <li>* Test time: 500+24/-0 hrs.</li> <li>* To apply voltage : rated voltage.</li> <li>* Before initial measurement (Class II only): To apply test voltage for 1hr at 40°C and then set for 24±2 hrs a t room temp.</li> <li>* Measurement to be made after keeping at room temp. for 24±2 hrs.</li> </ul>	<ul> <li>* No remarkable damage.</li> <li>* Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger. X7R: within ±12.5% Y5V: within ±30%</li> <li>* Q/D.F. value: NP0: Cap≥30pF, Q≥200; Cap&lt;30pF, Q≥100+10/3C</li> <li>X7R: Ur=50V, ≤3%; Ur=25V&amp;16V, ≤5%; Ur=10V, ≤7.5%</li> <li>Y5V: Ur=50V, ≤7.5%; Ur=16V, ≤10%</li> <li>* I.R.: ≥500MΩ or RxC≥25Ω-F whichever is smaller.</li> </ul>		
15.	High Temperature Load (Endurance)	<ul> <li>* Test temp.: NP0, X7R: 125±3°C Y5V: 85±3°C</li> <li>* To apply voltage: 200% of rated voltage.</li> <li>* Test time: 1000+24/-0 hrs.</li> <li>*Before initial measurement (Class II only): To apply test voltage for 1hr at test temp. and then set for 24±2 hrs at room temp.</li> <li>*Measurement to be made after keeping at room temp. for 24±2 hrs</li> </ul>	* No remarkable damage. * Cap change: NPO: within ±3.0% or ±0.3pF whichever is larger. X7R: within ±12.5% Y5V: within ±30% * Q/D.F. value: NPO: Cap≥30pF, Q≥350 10pF≤Cap<30pF, Q≥275+2.5C Cap<10pF, Q≥200+10C X7R: Ur=50V, ≤3%; Ur=25V&16V, ≤5%; Ur=10V, ≤7.5% Y5V: Ur=50V, ≤7.5%; Ur=16V, ≤10% * I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.		

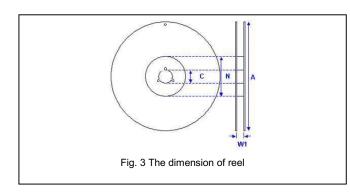


# **APPENDIXES**

#### Tape & reel dimensions

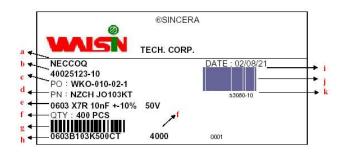


Size	4x0402	4x0603
Thickness	Т	В
A <sub>0</sub>	1.50±0.10	2.00±0.10
B <sub>0</sub>	2.30±0.10	3.50±0.10
Т	0.95±0.05	0.95±0.05
K <sub>0</sub>	-	-
w	8.00±0.10	8.00±0.10
P <sub>0</sub>	4.00±0.10	4.00±0.10
10xP₀	40.0±0.10	40.0±0.10
<b>P</b> <sub>1</sub>	4.00±0.10	4.00±0.10
P <sub>2</sub>	2.00±0.05	2.00±0.05
Do	1.55±0.05	1.50±0.05
D <sub>1</sub>	-	-
E	1.75±0.05	1.75±0.10
F	3.50±0.05	3.50±0.05



Size	4x0402, 4x0603
Reel size	7"
С	13.0+0.5/-0.2
<b>W</b> 1	8.4+1.5/-0
Α	178.0±0.10
Ν	60.0+1/-0

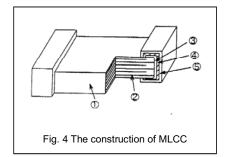
#### Description of customer label



- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
  - . Serial number of label

#### Constructions

No.	Nan	ie	NP0, X7R, Y5V
0	Ceramic r	naterial	BaTiO₃ based
2	Inner ele	ctrode	Ni
3		Inner layer	Cu
4	Termination	Middle layer	Ni
5		Outer layer	Sn (Matt)



#### Storage and handling conditions

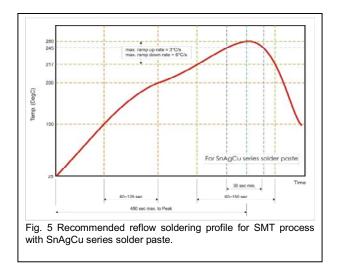
- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

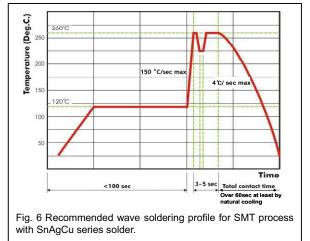
Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

#### Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of  $N_2$  within oven are recommended.







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